



Material Content Data Sheet



Sales Product Name		BTS3035TF		Issued		19. January 2018		
MA#		MA001328770						
Package		PG-TO252-3-313		Weight*		318.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.529	0.48	0.48	4803	4803
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		463	
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	copper	7440-50-8	147.096	46.20	46.26	461969	462571
wire	non noble metal	aluminium	7429-90-5	9.368	2.94	2.94	29422	29422
encapsulation	organic material	carbon black	1333-86-4	1.343	0.42		4217	
	plastics	epoxy resin	-	23.498	7.38		73797	
	inorganic material	silicondioxide	60676-86-0	109.433	34.37	42.17	343683	421697
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11746	11746
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4461	4472
solder	noble metal	silver	7440-22-4	0.040	0.01		125	
	non noble metal	tin	7440-31-5	0.032	0.01		100	
	non noble metal	lead	7439-92-1	1.515	0.48	0.50	4758	4983
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.02	6.03	60228	60306
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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